

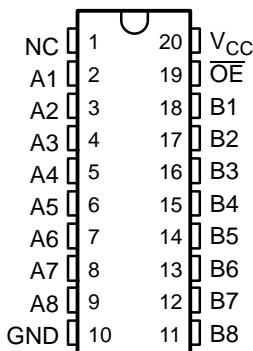
## FEATURES

- **High-Bandwidth Data Path (up to 500 MHz<sup>(1)</sup>)**
- **Equivalent to IDTQS3VH384 Device**
- **5-V Tolerant I/Os With Device Powered Up or Powered Down**
- **Low and Flat ON-State Resistance ( $r_{on}$ ) Characteristics Over Operating Range ( $r_{on} = 4 \Omega$  Typ)**
- **Rail-to-Rail Switching on Data I/O Ports**
  - 0- to 5-V Switching With 3.3-V  $V_{CC}$
  - 0- to 3.3-V Switching With 2.5-V  $V_{CC}$
- **Bidirectional Data Flow With Near-Zero Propagation Delay**
- **Low Input/Output Capacitance Minimizes Loading and Signal Distortion ( $C_{IO(OFF)} = 3.5 \text{ pF}$  Typ)**
- **Fast Switching Frequency ( $f_{OE} = 20 \text{ MHz}$  Max)**

(1) For additional information regarding the performance characteristics of the CB3Q family, refer to the TI application report, *CBT-C, CB3T, and CB3Q Signal-Switch Families*, literature number SCDA008.

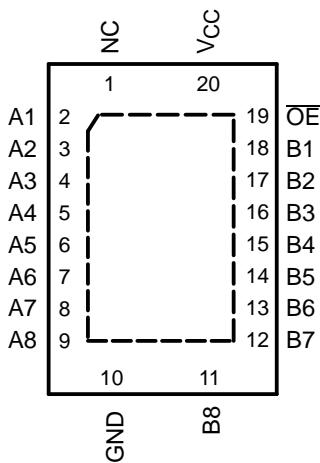
- **Data and Control Inputs Provide Undershoot Clamp Diodes**
- **Low Power Consumption ( $I_{CC} = 1 \text{ mA}$  Typical)**
- **$V_{CC}$  Operating Range From 2.3 V to 3.6 V**
- **Data I/Os Support 0- to 5-V Signaling Levels (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V)**
- **Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs**
- **$I_{off}$  Supports Partial-Power-Down Mode Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)
- **Supports Both Digital and Analog Applications: PCI Interface, Differential Signal Interface, Memory Interleaving, Bus Isolation, Low-Distortion Signal Gating**

DBQ, DGV, OR PW PACKAGE  
(TOP VIEW)



NC - No internal connection

RGY PACKAGE  
(TOP VIEW)



NC - No internal connection

## DESCRIPTION/ORDERING INFORMATION

The SN74CB3Q3245 is a high-bandwidth FET bus switch utilizing a charge pump to elevate the gate voltage of the pass transistor, providing a low and flat ON-state resistance ( $r_{on}$ ). The low and flat ON-state resistance allows for minimal propagation delay and supports rail-to-rail switching on the data input/output (I/O) ports. The device also features low data I/O capacitance to minimize capacitive loading and signal distortion on the data bus. Specifically designed to support high-bandwidth applications, the SN74CB3Q3245 provides an optimized interface solution ideally suited for broadband communications, networking, and data-intensive computing systems.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

## DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The SN74CB3Q3245 is organized as an 8-bit bus switch with a single output-enable ( $\overline{OE}$ ) input. When  $\overline{OE}$  is low, the bus switch is ON and the A port is connected to the B port, allowing bidirectional data flow between ports. When  $\overline{OE}$  is high, the bus switch is OFF and a high-impedance state exists between the A and B ports.

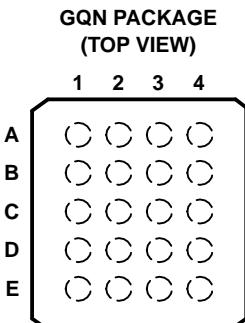
This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry prevents damaging current backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Tape and reel	SN74CB3Q3245RGYR	BU245
	SSOP (QSOP) – DBQ	Tape and reel	SN74CB3Q3245DBQR	CB3Q3245
	TSSOP – PW	Tube	SN74CB3Q3245PW	BU245
		Tape and reel	SN74CB3Q3245PWR	
	TVSOP – DGV	Tape and reel	SN74CB3Q3245DGVR	BU245
	VFBGA – GQN	Tape and reel	SN74CB3Q3245GQNR	BU245

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



### TERMINAL ASSIGNMENTS<sup>(1)</sup>

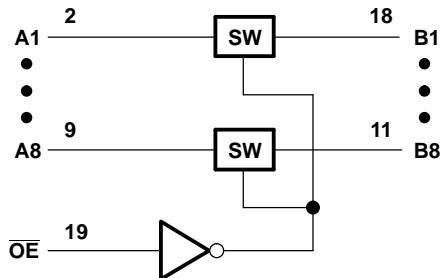
	1	2	3	4
<b>A</b>	A1	NC	$V_{CC}$	$\overline{OE}$
<b>B</b>	A3	B2	A2	B1
<b>C</b>	A5	A4	B4	B3
<b>D</b>	A7	B6	A6	B5
<b>E</b>	GND	A8	B8	B7

(1) NC - No internal connection

### FUNCTION TABLE

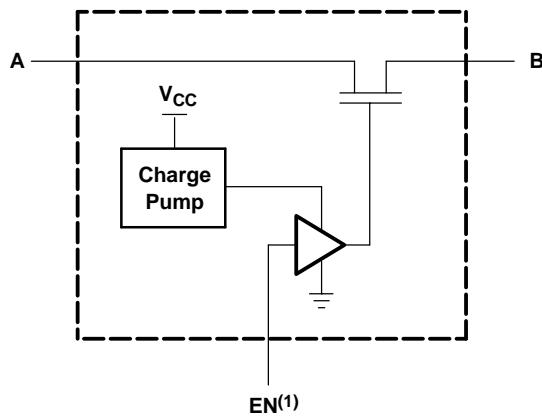
INPUT $\overline{OE}$	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect

LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the DBQ, DGV, PW, and RGY packages.

SIMPLIFIED SCHEMATIC, EACH FET SWITCH (SW)



(1) EN is the internal enable signal applied to the switch.

**SN74CB3Q3245**  
**8-BIT FET BUS SWITCH**  
**2.5-V/3.3-V LOW-VOLTAGE HIGH-BANDWIDTH BUS SWITCH**

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**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	4.6	V
$V_{IN}$	Control input voltage range <sup>(2)(3)</sup>		-0.5	7	V
$V_{I/O}$	Switch I/O voltage range <sup>(2)(3)(4)</sup>		-0.5	7	V
$I_{IK}$	Control input clamp current	$V_{IN} < 0$		-50	mA
$I_{I/OK}$	I/O port clamp current	$V_{I/O} < 0$		-50	mA
$I_{IO}$	ON-state switch current <sup>(5)</sup>			$\pm 64$	mA
	Continuous current through $V_{CC}$ or GND			$\pm 100$	mA
$\theta_{JA}$	Package thermal impedance	DBQ package <sup>(6)</sup>		68	°C/W
		DGV package <sup>(6)</sup>		92	
		GQN package <sup>(6)</sup>		78	
		PW package <sup>(6)</sup>		83	
		RGY package <sup>(7)</sup>		37	
$T_{stg}$	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4)  $V_I$  and  $V_O$  are used to denote specific conditions for  $V_{I/O}$ .
- (5)  $I_I$  and  $I_O$  are used to denote specific conditions for  $I_{I/O}$ .
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.
- (7) The package thermal impedance is calculated in accordance with JESD 51-5.

**Recommended Operating Conditions<sup>(1)</sup>**

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage		2.3	3.6	V
$V_{IH}$	High-level control input voltage	$V_{CC} = 2.3$ V to 2.7 V	1.7	5.5	V
		$V_{CC} = 2.7$ V to 3.6 V	2	5.5	
$V_{IL}$	Low-level control input voltage	$V_{CC} = 2.3$ V to 2.7 V	0	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	0	0.8	
$V_{I/O}$	Data input/output voltage		0	5.5	V
$T_A$	Operating free-air temperature		-40	85	°C

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### Electrical Characteristics<sup>(1)</sup>

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP <sup>(2)</sup>	MAX	UNIT
$V_{IK}$		$V_{CC} = 3.6$ V, $I_I = -18$ mA					-1.8	V
$I_{IN}$	Control inputs	$V_{CC} = 3.6$ V, $V_{IN} = 0$ to $5.5$ V					$\pm 1$	$\mu A$
$I_{OZ}^{(3)}$		$V_{CC} = 3.6$ V, $V_O = 0$ to $5.5$ V, $V_I = 0$ , $V_{IN} = V_{CC}$ or GND					$\pm 1$	$\mu A$
$I_{off}$		$V_{CC} = 0$ , $V_O = 0$ to $5.5$ V, $V_I = 0$					1	$\mu A$
$I_{CC}$		$V_{CC} = 3.6$ V, $I_{I/O} = 0$ , Switch ON or OFF, $V_{IN} = V_{CC}$ or GND			1	2		mA
$\Delta I_{CC}^{(4)}$	Control inputs	$V_{CC} = 3.6$ V, One input at $3$ V, Other inputs at $V_{CC}$ or GND					30	$\mu A$
$I_{CCD}^{(5)}$	Per control input	$V_{CC} = 3.6$ V, A and B ports open, Control input switching at 50% duty cycle			0.30	0.35		$mA/$ MHz
$C_{in}$	Control inputs	$V_{CC} = 3.3$ V, $V_{IN} = 5.5$ V, $3.3$ V, or 0			2.5	3.5		pF
$C_{io(OFF)}$		$V_{CC} = 3.3$ V, Switch OFF, $V_{IN} = V_{CC}$ or GND, $V_{I/O} = 5.5$ V, $3.3$ V, or 0			3.5	5		pF
$C_{io(ON)}$		$V_{CC} = 3.3$ V, Switch ON, $V_{IN} = V_{CC}$ or GND, $V_{I/O} = 5.5$ V, $3.3$ V, or 0			9	11		pF
$r_{on}^{(6)}$	$V_{CC} = 2.3$ V, TYP at $V_{CC} = 2.5$ V	$V_I = 0$ ,	$I_O = 30$ mA			4	8	$\Omega$
		$V_I = 1.7$ V,	$I_O = -15$ mA			4.5	9	
	$V_{CC} = 3$ V	$V_I = 0$ ,	$I_O = 30$ mA			4	6	
		$V_I = 2.4$ V,	$I_O = -15$ mA			4	8	

(1)  $V_{IN}$  and  $I_{IN}$  refer to control inputs.  $V_I$ ,  $V_O$ ,  $I_I$ , and  $I_O$  refer to data pins.

(2) All typical values are at  $V_{CC} = 3.3$  V (unless otherwise noted),  $T_A = 25^\circ C$ .

(3) For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

(5) This parameter specifies the dynamic power-supply current associated with the operating frequency of a single control input (see Figure 2).

(6) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

### Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5$ V $\pm 0.2$ V		$V_{CC} = 3.3$ V $\pm 0.3$ V		UNIT
			MIN	MAX	MIN	MAX	
$f_{OE}^{(1)}$	$\overline{OE}$	A or B		10		20	MHz
$t_{pd}^{(2)}$	A or B	B or A		0.12		0.20	ns
$t_{en}$	$\overline{OE}$	A or B	1.5	7.5	1.5	6.5	ns
$t_{dis}$	$\overline{OE}$	A or B	1	6.5	1	6.5	ns

(1) Maximum switching frequency for control input ( $V_O > V_{CC}$ ,  $V_I = 5$  V,  $R_L \geq 1$  M $\Omega$ ,  $C_L = 0$ )

(2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

**SN74CB3Q3245**  
**8-BIT FET BUS SWITCH**  
**2.5-V/3.3-V LOW-VOLTAGE HIGH-BANDWIDTH BUS SWITCH**

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 **TEXAS**  
**INSTRUMENTS**  
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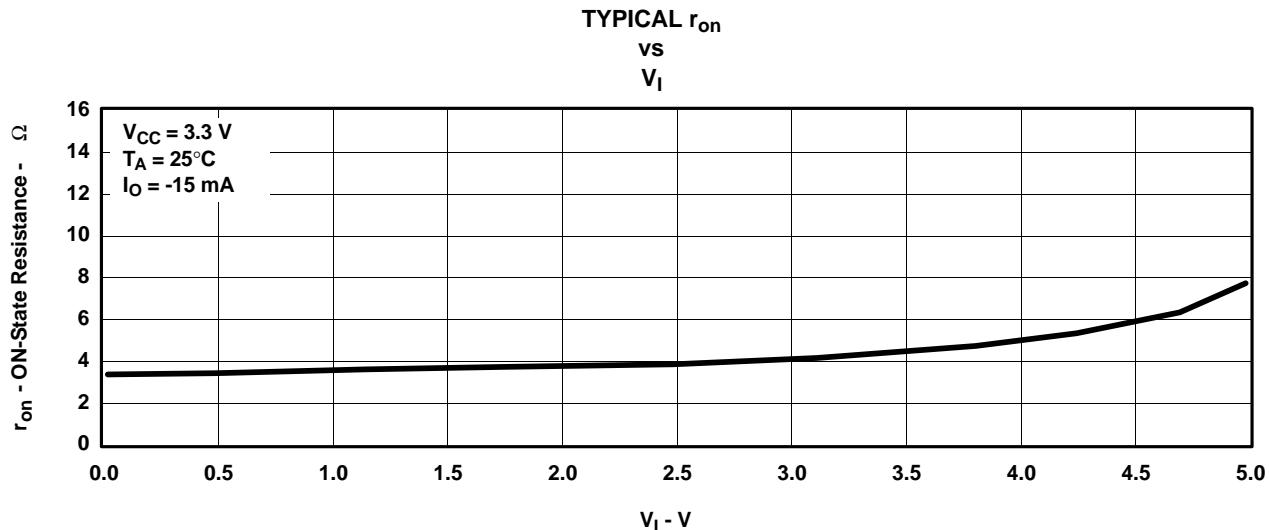


Figure 1. Typical  $r_{on}$  vs  $V_I$

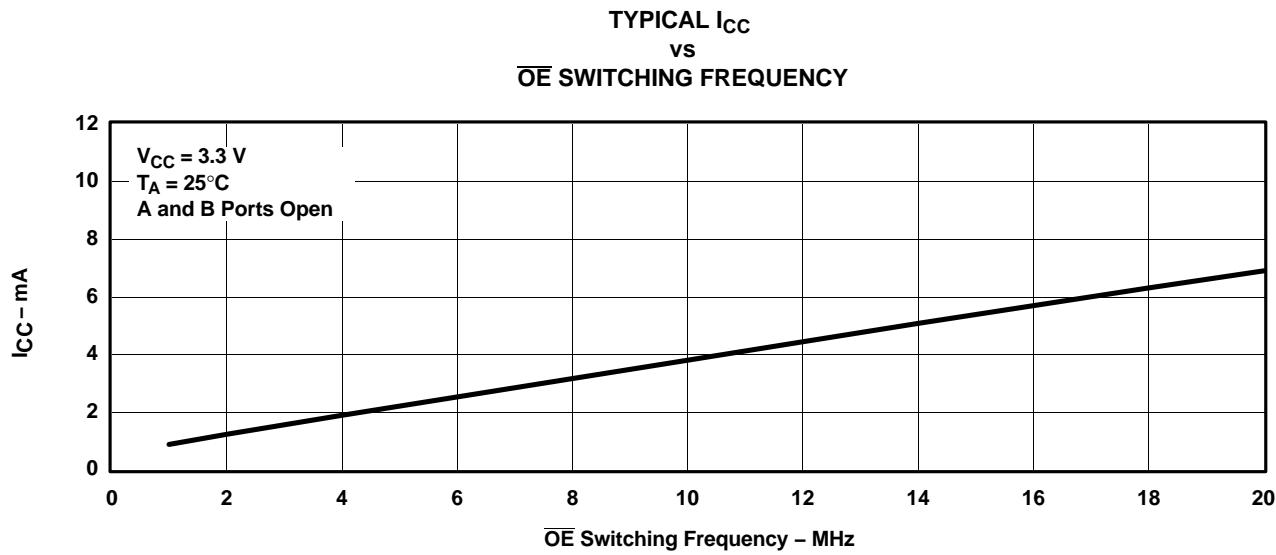
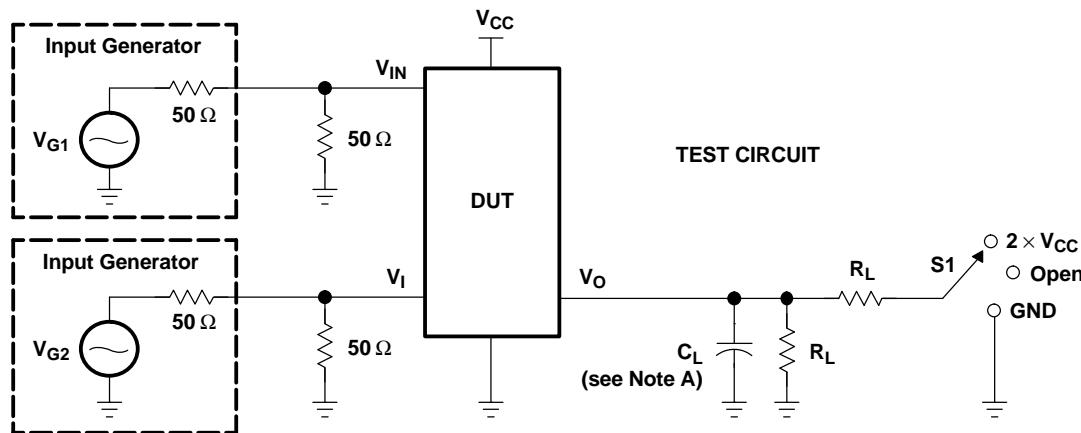
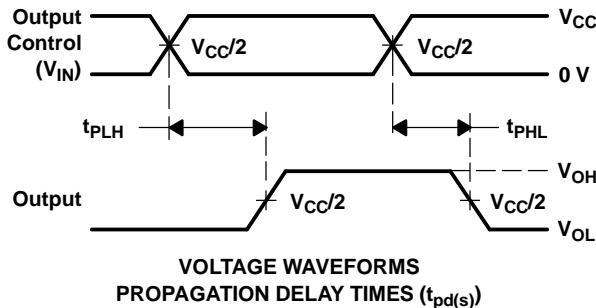


Figure 2. Typical  $I_{CC}$  vs  $\overline{OE}$  Switching Frequency

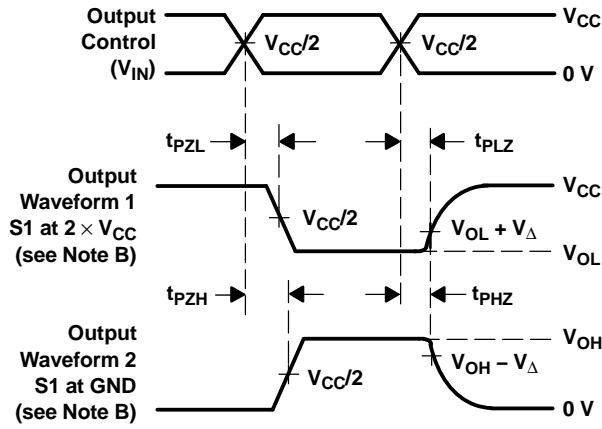
### PARAMETER MEASUREMENT INFORMATION



TEST	$V_{CC}$	$S1$	$R_L$	$V_I$	$C_L$	$V_\Delta$
$t_{pd(s)}$	$2.5\text{ V} \pm 0.2\text{ V}$ $3.3\text{ V} \pm 0.3\text{ V}$	Open Open	$500\text{ }\Omega$ $500\text{ }\Omega$	$V_{CC}$ or GND $V_{CC}$ or GND	$30\text{ pF}$ $50\text{ pF}$	
$t_{PLZ}/t_{PZL}$	$2.5\text{ V} \pm 0.2\text{ V}$ $3.3\text{ V} \pm 0.3\text{ V}$	$2 \times V_{CC}$ $2 \times V_{CC}$	$500\text{ }\Omega$ $500\text{ }\Omega$	GND GND	$30\text{ pF}$ $50\text{ pF}$	$0.15\text{ V}$ $0.3\text{ V}$
$t_{PHZ}/t_{PZH}$	$2.5\text{ V} \pm 0.2\text{ V}$ $3.3\text{ V} \pm 0.3\text{ V}$	GND GND	$500\text{ }\Omega$ $500\text{ }\Omega$	$V_{CC}$ $V_{CC}$	$30\text{ pF}$ $50\text{ pF}$	$0.15\text{ V}$ $0.3\text{ V}$



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES ( $t_{pd(s)}$ )



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_O = 50\text{ }\Omega$ ,  $t_r \leq 2.5\text{ ns}$ ,  $t_f \leq 2.5\text{ ns}$ .
- The outputs are measured one at a time, with one transition per measurement.
- $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd(s)}$ . The tpd propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
- All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74CB3Q3245DBQRE4	ACTIVE	SSOP	DBQ	20		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
74CB3Q3245DBQRG4	ACTIVE	SSOP	DBQ	20		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
74CB3Q3245DGVR4	ACTIVE	TVSOP	DGV	20		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
74CB3Q3245DGVRG4	ACTIVE	TVSOP	DGV	20		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
74CB3Q3245RGYRG4	ACTIVE	VQFN	RGY	20	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245DBQR	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CB3Q3245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245DGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245GQNR	OBsolete	BGA MICROSTAR JUNIOR	GQN	20		TBD	Call TI	Call TI	-40 to 85		
SN74CB3Q3245PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245RGYR	ACTIVE	VQFN	RGY	20	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CB3Q3245ZQNR	ACTIVE	BGA MICROSTAR JUNIOR	ZQN	20	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	BU245	<span style="background-color: red; color: white; padding: 2px;">Samples</span>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

**(2)** Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

**(3)** MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**(4)** There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

**(5)** Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

**(6)** Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

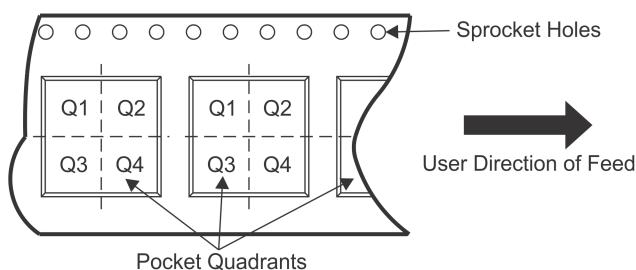
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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

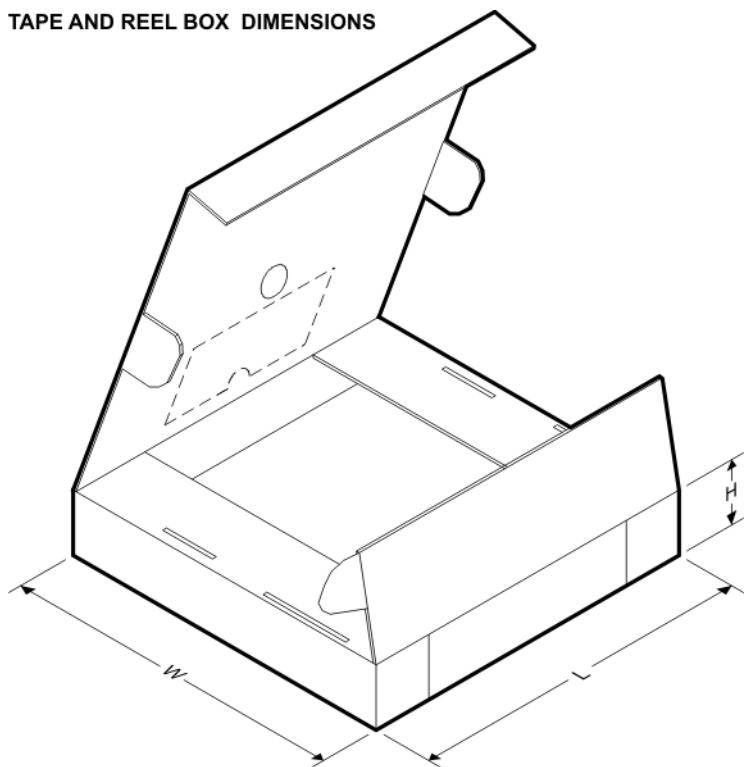
**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CB3Q3245DBQR	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74CB3Q3245DGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CB3Q3245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74CB3Q3245RGYR	VQFN	RGY	20	3000	330.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1
SN74CB3Q3245ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	330.0	12.4	3.3	4.3	1.6	8.0	12.0	Q1

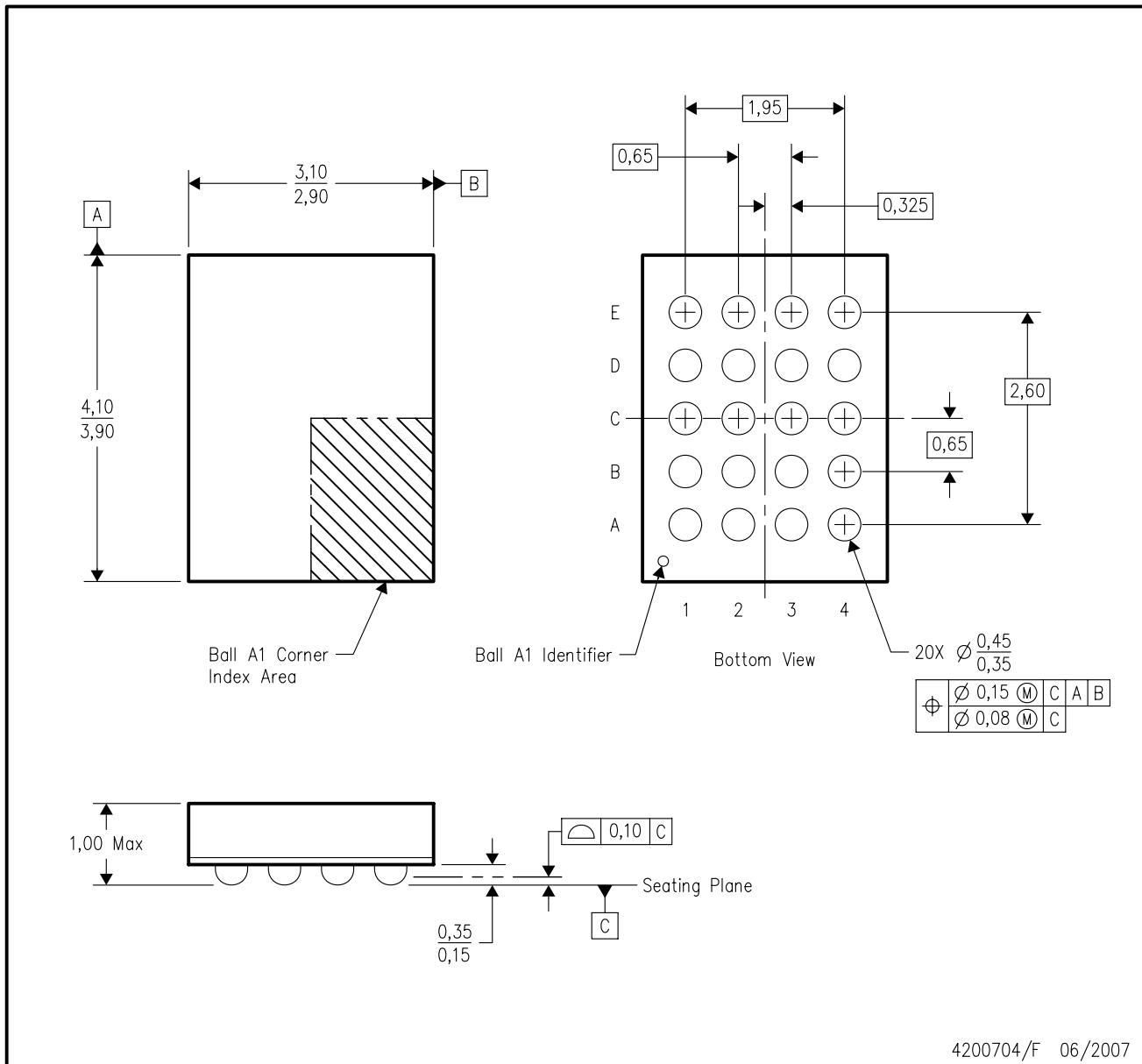
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CB3Q3245DBQR	SSOP	DBQ	20	2500	367.0	367.0	38.0
SN74CB3Q3245DGVR	TVSOP	DGV	20	2000	367.0	367.0	35.0
SN74CB3Q3245PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74CB3Q3245RGYR	VQFN	RGY	20	3000	367.0	367.0	35.0
SN74CB3Q3245ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	338.1	338.1	20.6

## GQN (R-PBGA-N20)

## PLASTIC BALL GRID ARRAY

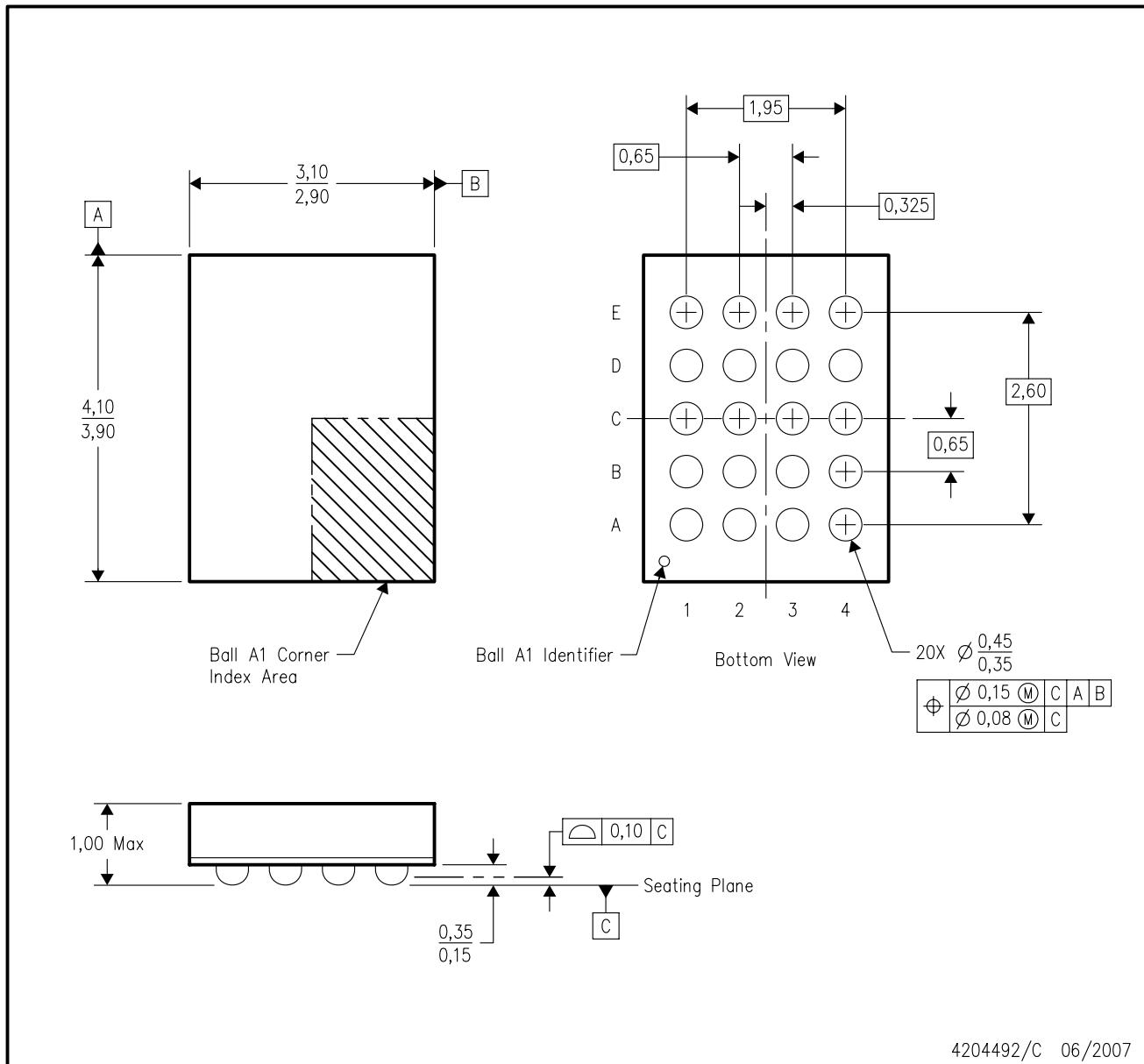


NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Falls within JEDEC MO-285 variation BC-2.
- This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

## ZQN (R-PBGA-N20)

## PLASTIC BALL GRID ARRAY



4204492/C 06/2007

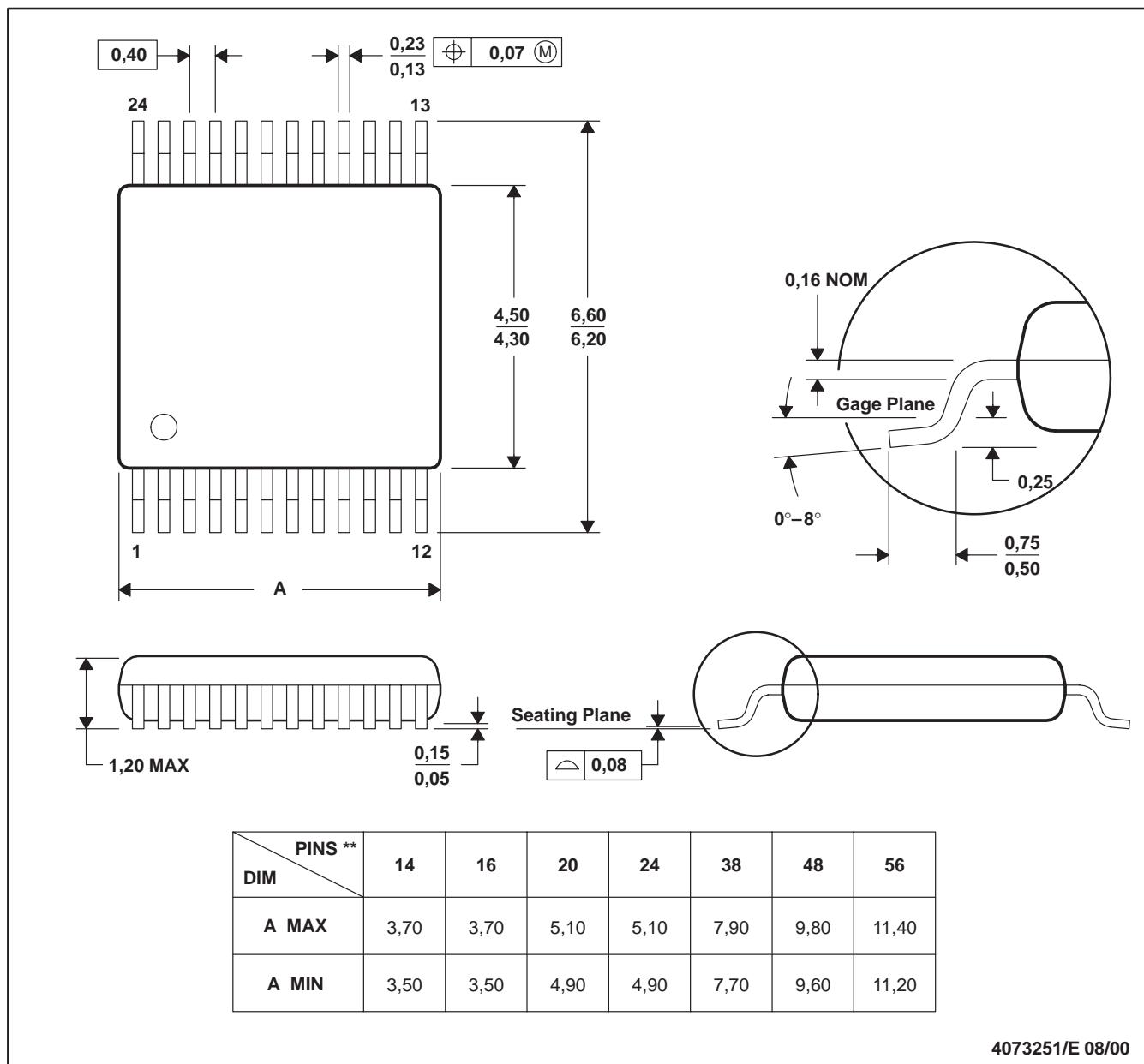
NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Falls within JEDEC MO-285 variation BC-2.
- This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

**24 PINS SHOWN**

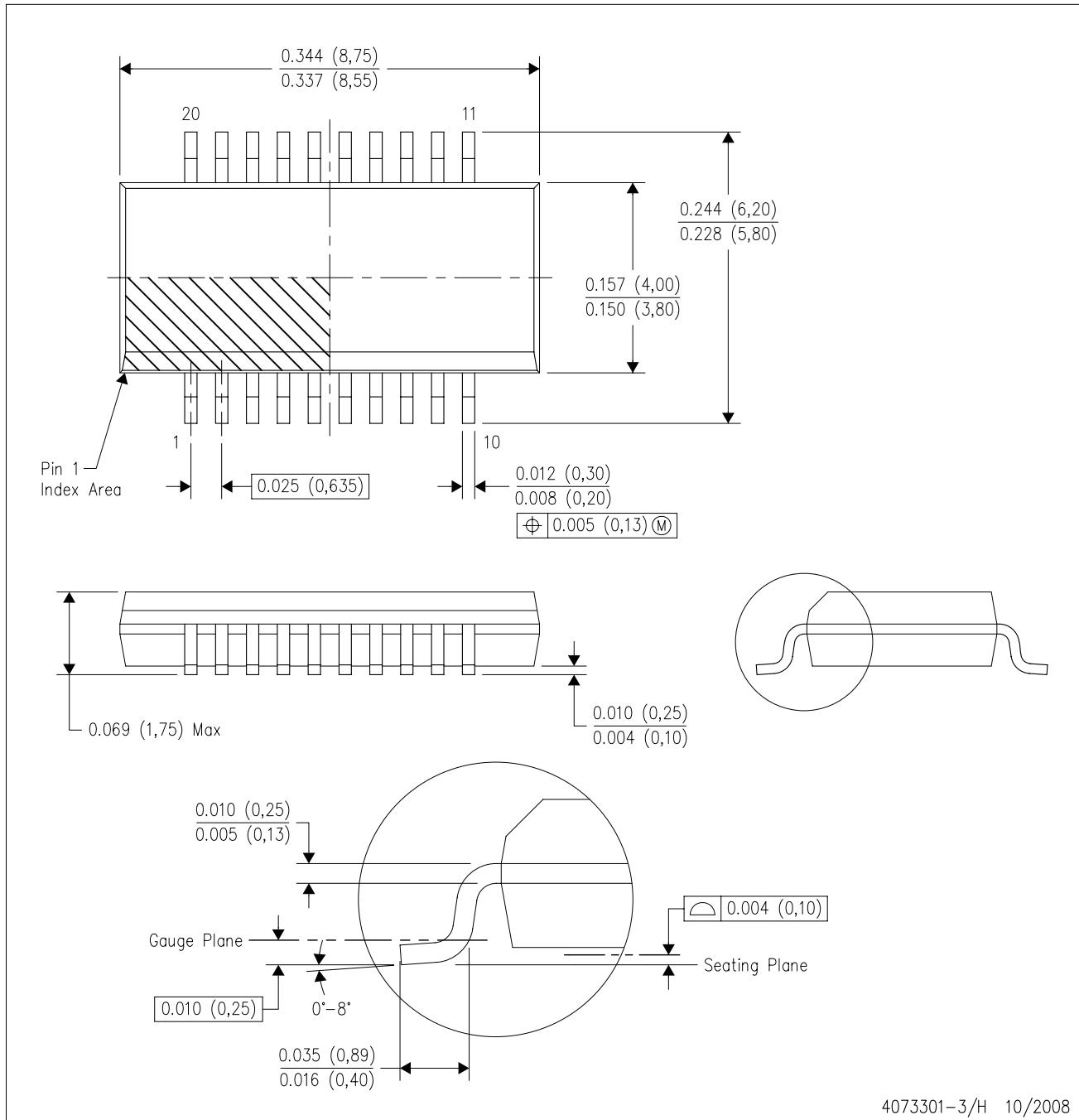


NOTES: A. All linear dimensions are in millimeters.  
B. This drawing is subject to change without notice.  
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
D. Falls within JEDEC: 24/48 Pins – MO-153  
14/16/20/56 Pins – MO-194

14/16/20/56 Pins – MO-194

DBQ (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



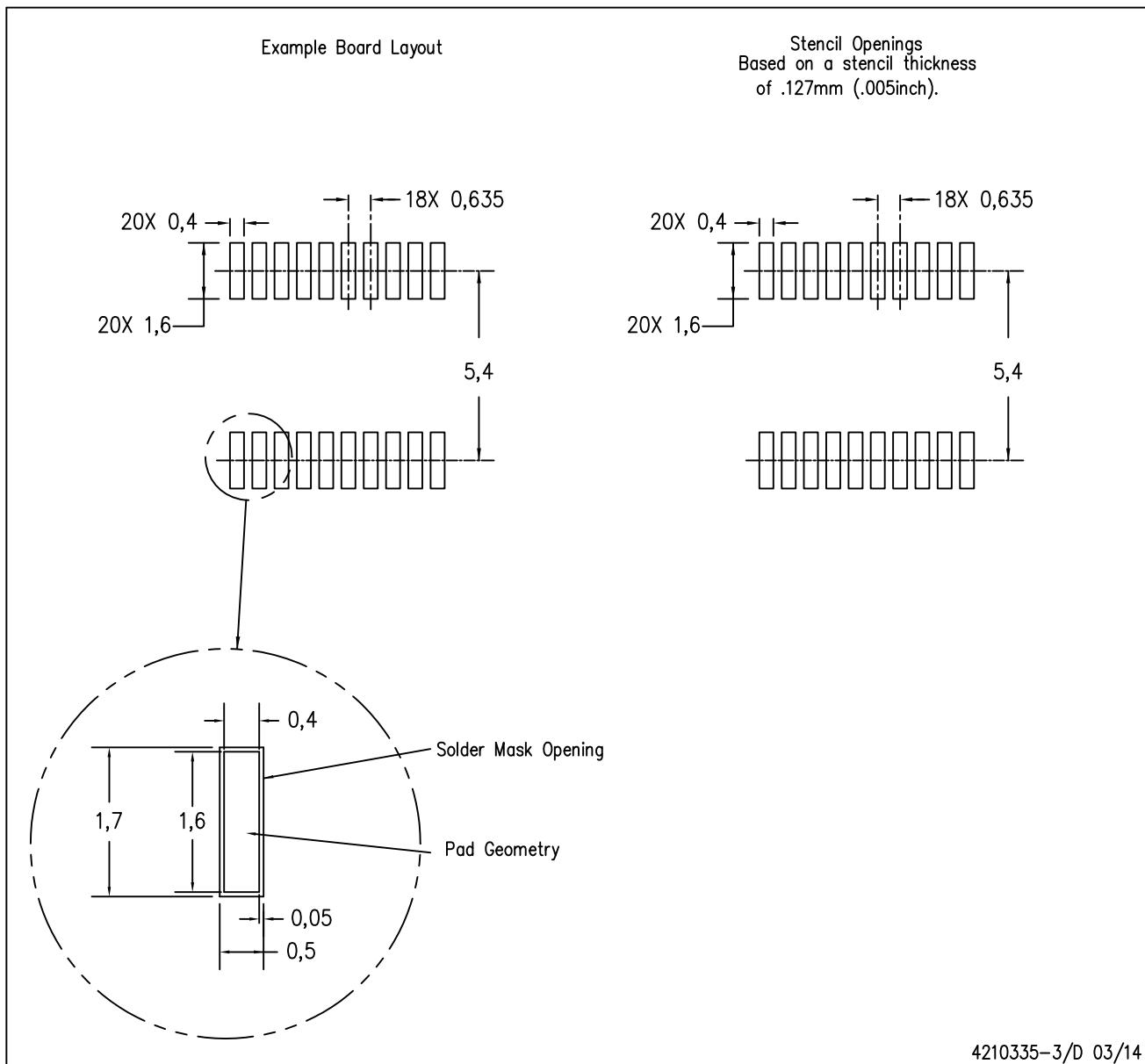
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
- Falls within JEDEC MO-137 variation AD.

## LAND PATTERN DATA

DBQ (R-PDSO-G20)

PLASTIC SMALL OUTLINE PACKAGE

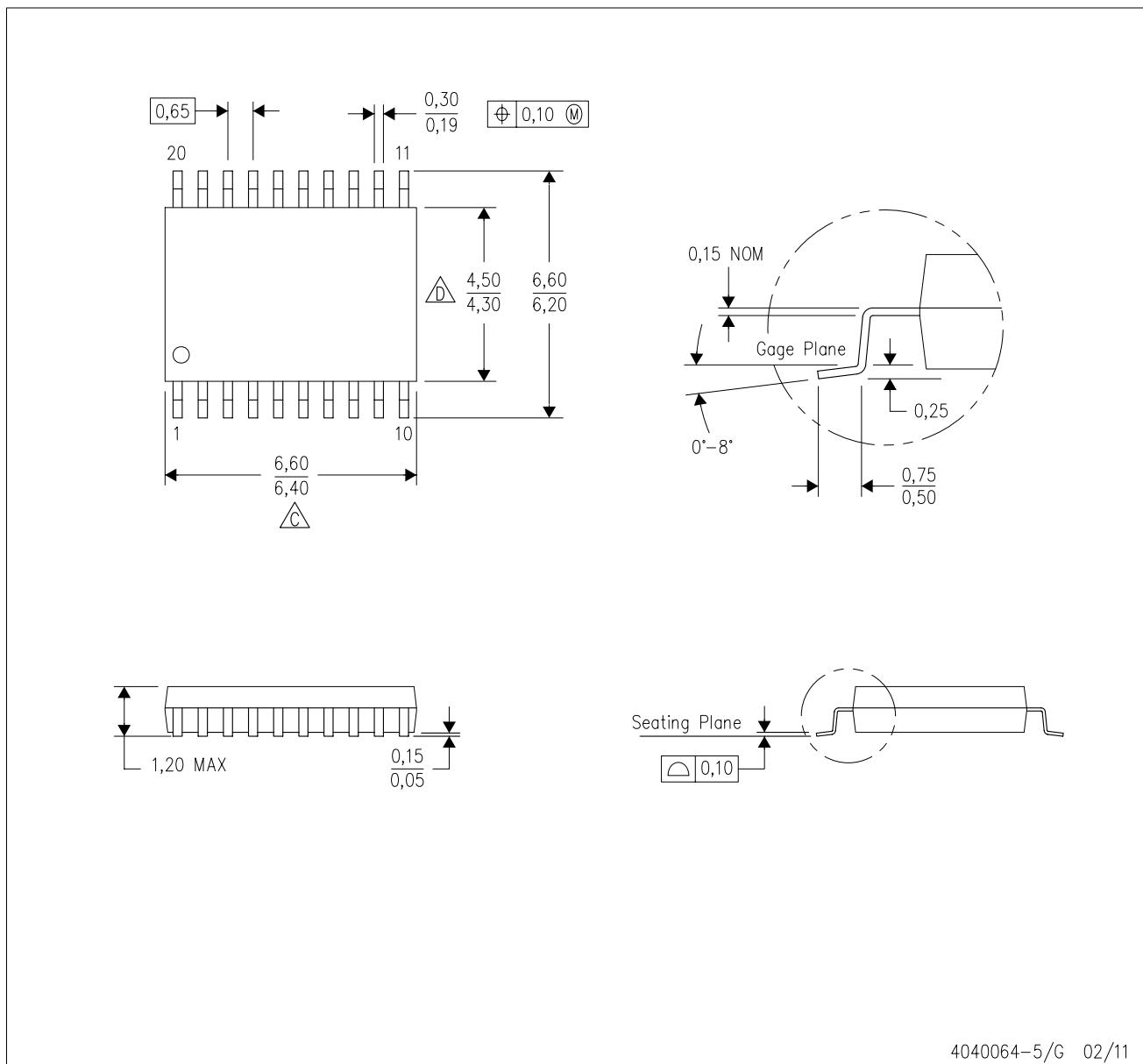


NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

 C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

 D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

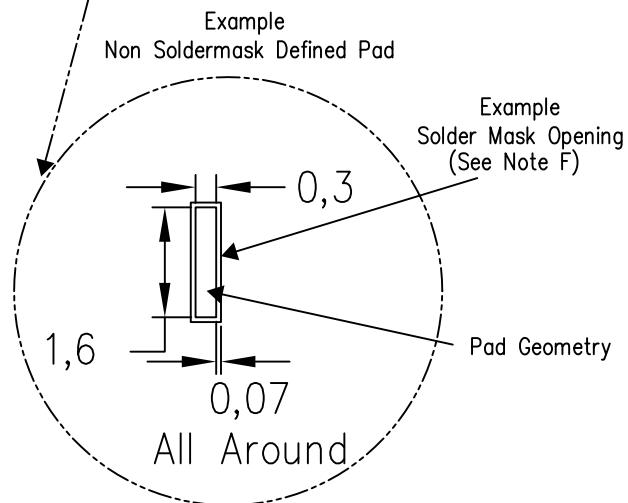
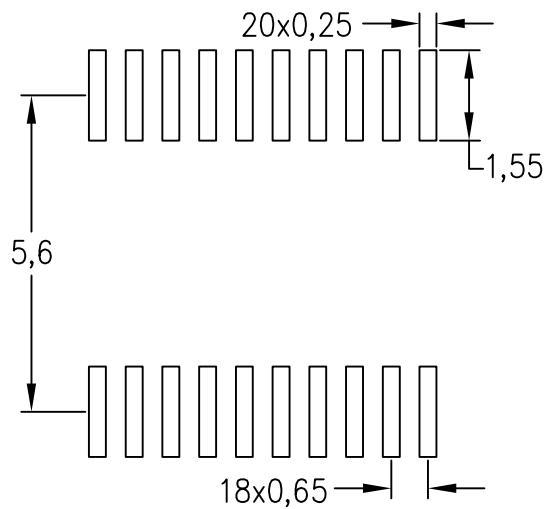
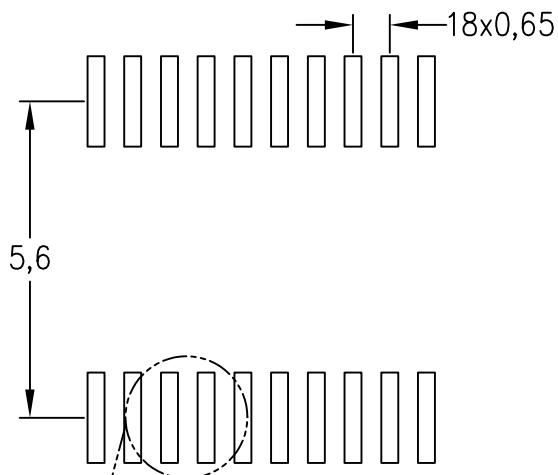
4040064-5/G 02/11

## PW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE

## Example Board Layout

Based on a stencil thickness  
of .127mm (.005inch).



4211284-5/F 12/12

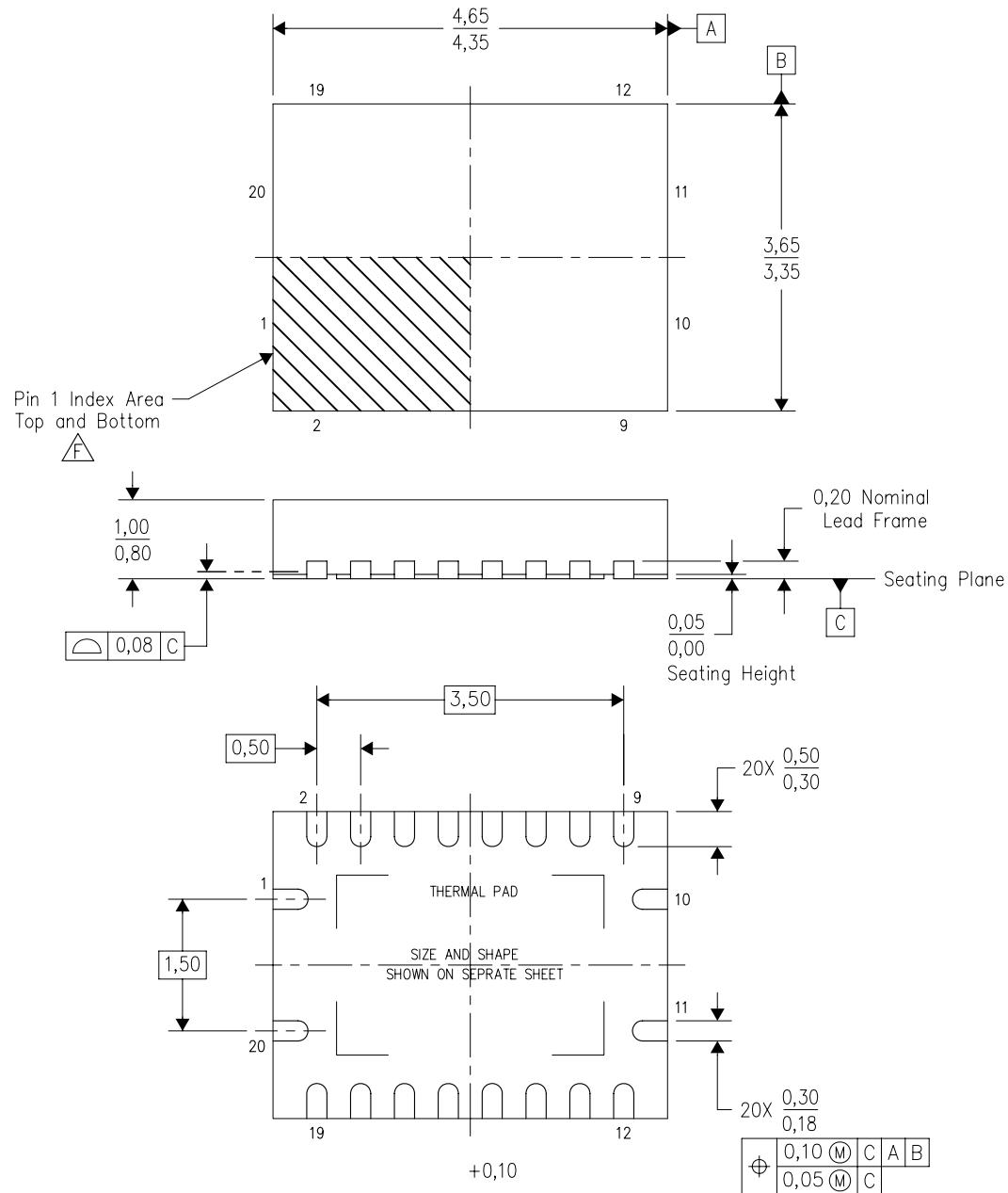
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## MECHANICAL DATA

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



### Bottom View

4203539-4/l 06/2011

NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

 F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.  
The Pin 1 identifiers are either a molded, marked, or metal feature.

- G. Package complies to JEDEC MO-241 variation BA.

# THERMAL PAD MECHANICAL DATA

RGY (R-PVQFN-N20)

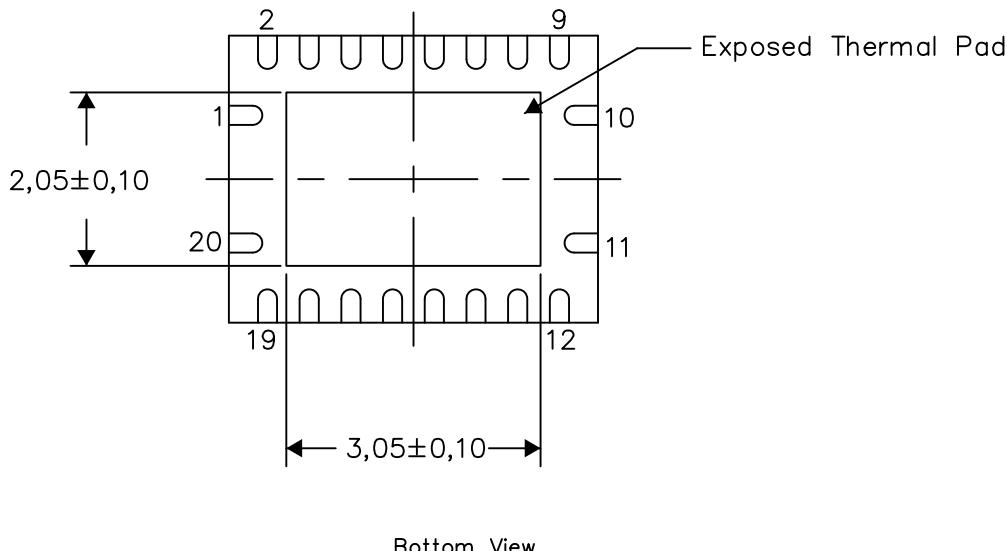
PLASTIC QUAD FLATPACK NO-LEAD

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

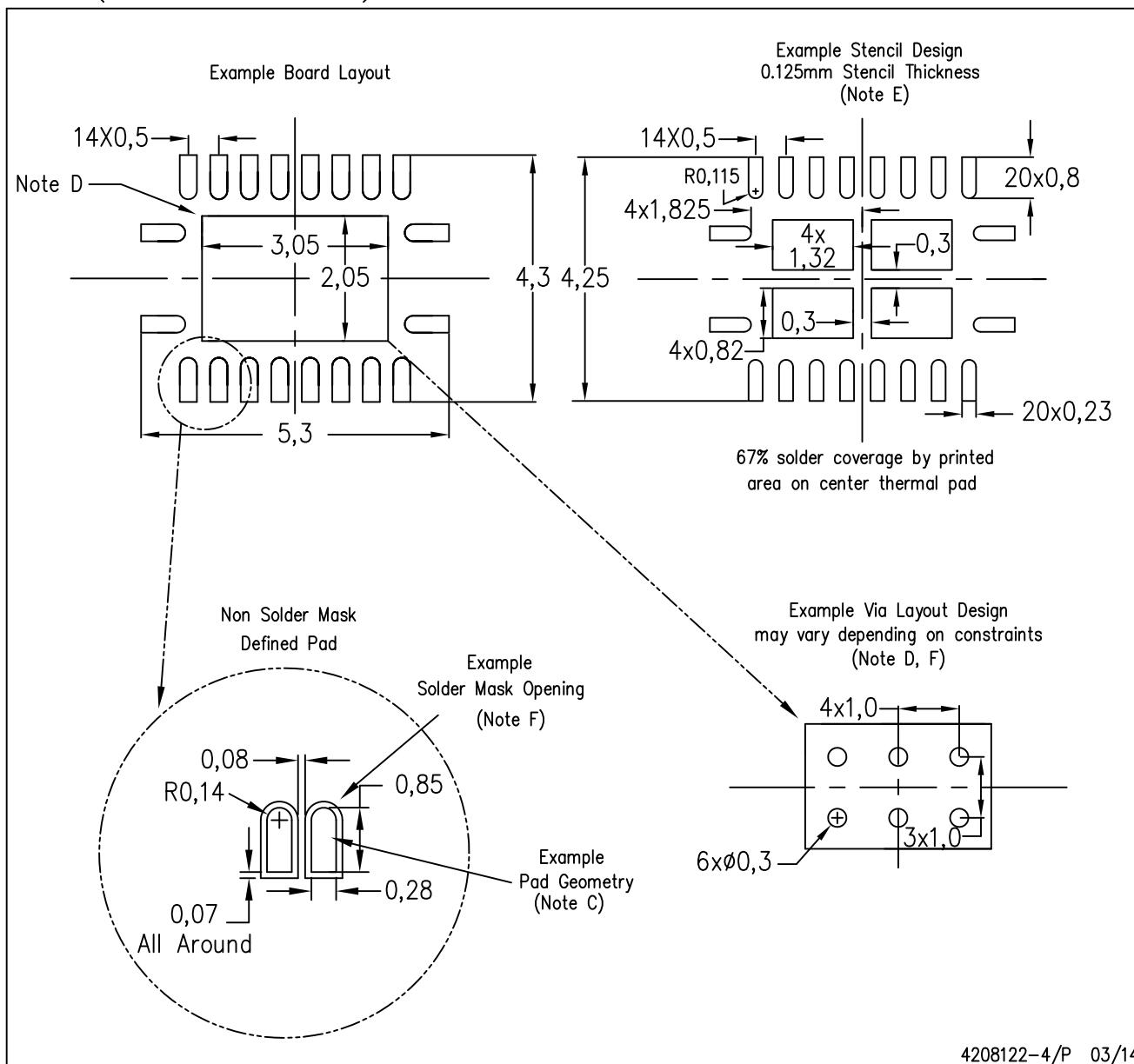
Exposed Thermal Pad Dimensions

4206353-4/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-4/P 03/14

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
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